

Appl. No. 10/758,822
Amdt. Dated March 20, 2006
Reply to Office Action of September 21, 2005

Docket No. CE11518JGN

Amendments to the Specification:

On page 3, lines 13-22, please replace with the following paragraph:

However, if components such as electrical connectors which are mechanically stressed are to be included on a PWB it is desirable to secure these with high strength solder joints. In the past engineers resorted to through hole mounting in order to secure mechanically stressed components such as electrical connectors. However, in the interest of simplified more cost effective manufacturing it is desirable to use a single SMT soldering process to secure all components. Conventional wisdom dictates that in order to secure mechanically stressed components using SMT a thicker layer of solder paste be applied, however this is at odds with the above mentioned goal of reducing pad size and inter-pad spacing for microchips and discrete components.

On page 13, lines 15-22, please replace with the following paragraph:

Referring to FIGs. 10-14 an additional embodiment will be described. FIG. 10 is a flow chart of the additional embodiment of a process of manufacturing a populated printed wiring board. Referring to FIG. 10, in block 1002 a PWB having exposed copper pads is fabricated. FIG. 11 is a fragmentary top view of a second PWB 1100 at a first stage of the process shown in FIG. 10. As shown in FIG. 11, the second PWB 1100 comprises a first copper pad 1102, a second copper pad 1104, a third copper pad 1106, and a fourth copper pad 1108 arranged on a surface 1110 of the second PWB 1100.